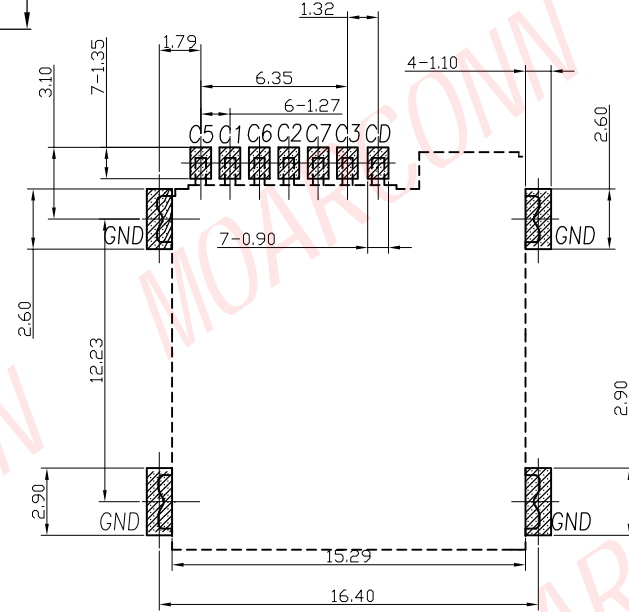
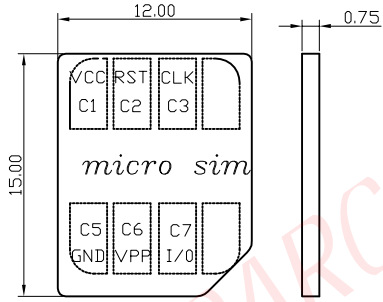
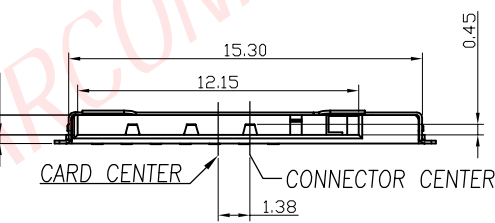
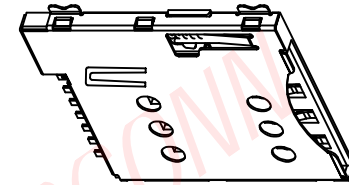
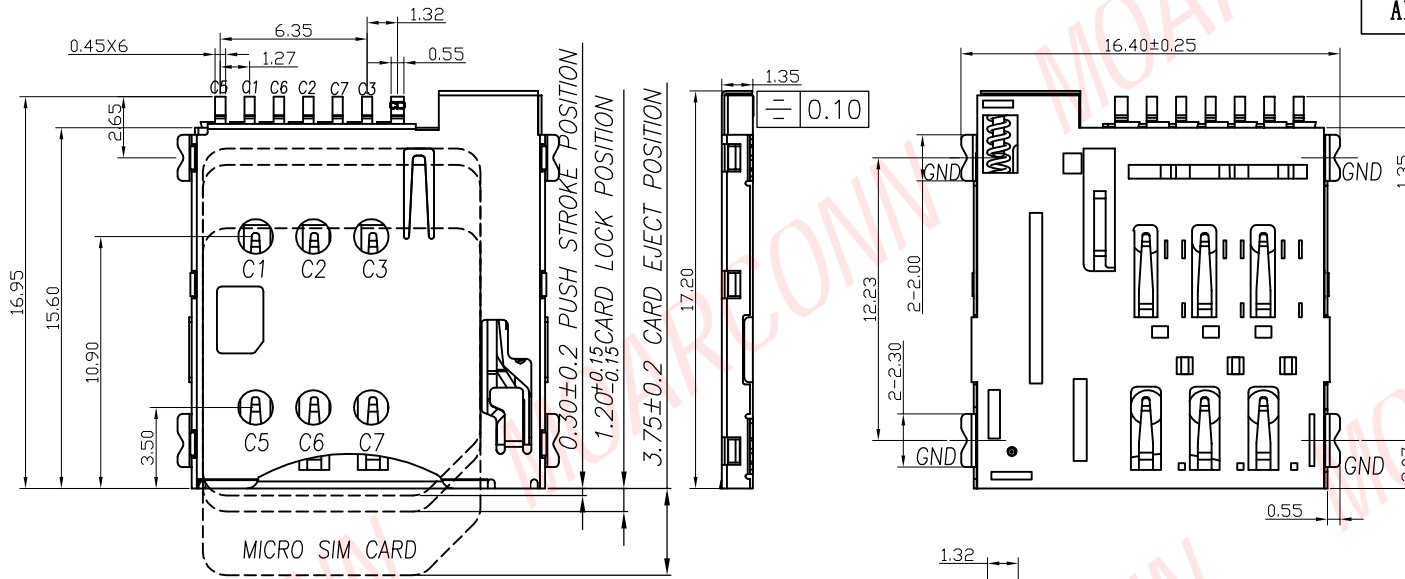


All materials, plating and process meet HF requirements.



Specification

MATERIAL:
 Insulator: High Temperature Thermoplastic, UL 94V-0.
 Contact: Copper Alloy
 SHELL: Stainless steel

CONTACT PLATING:
 Underplate: 50u' Min. Ni Overall
 Contact And Solder Tails Area: 1u' Min. Au

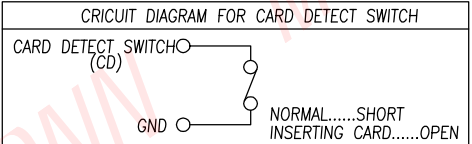
SHELL PLATING:
 Underplate: Plated 50u' Ni Overall
 Solder Tails Area: 1u' Min. Au

Electrical:
 Current Rating :0.5mA AC/DC max.
 Voltage Rating :125V AC/DC
 Ambient Temperature Range :-20° C~+60° C
 Storage Temperature Range :-40° C~+70° C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100m max.Ω
 Insulation Resistance:1000M min./500VDC
 Mating Cycles:10,000 Insertions
 产品耐温温度: 260° C ±5° C
 Mating Cycles:5,000-10,000 Insertions

SIM pin assignment	
PIN#	Name
C1	VCC 供电电压
C2	RST 重置
C3	CLK 时钟
C5	GND 接地
C6	VPP 程序电压
C7	I/O 输入输出

PCB 焊盘区
 下沉部位区

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05



MOARCONN
 MORE CONNECTIONS SMART FUTURE

DIMENSIONS INIT: mm
 UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.38
X.XX: ±	0.20
X.XXX: ±	0.15
ANGULAR: ±	3'

DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
PRODUCT NAME :	MICRO SIM CARD CONN. PUSH TYPE H:1.35mm	DRAWING:	FAJI
DATE:	2022.04.15	CHECK:	DATE:
PRODUCT NO. :	MS135-T1250-12-W	APPROVED:	DATE:
DRAWING NO. :	D-MS135-T1250-12-W	SCALE:	1:1
REVISION:	B	DWG ID:	C D
MARK:	FAJI	REV.:	B
DATE:	2022.04.15	PAGE:	1 OF 1

B	---	Collating Drawing	FAJI	2022.04.15
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				